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12/19/01

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10033854	12/19/2001	438	108	2823 2842	K. Nguyen

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**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met: <input type="checkbox"/> yes <input type="checkbox"/> no		42390P13267
Verified and Acknowledged Examiners's initials		
TITLE : Underfill materials dispensed in a flip chip package by way of a through hole		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L/Rev. 12-94

NOTICE OF ALLOWANCE MAILED		CLAMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheet Drwg.	Fig. Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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